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### NCE25GD135T

### 1350V, 25A, Trench NPT IGBT

#### **Features**

- Trench NPT( Non Punch Through) IGBT
- High speed switching
- Low saturation voltage: V<sub>CE(sat)</sub>=2.0V@I<sub>C</sub>=25A
- High input impedance

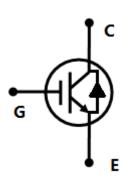
#### **Applications**

- Inductive heating, Microwave oven, Inverter, UPS, etc.
- Soft switching applications



Using advanced Trench NPT technology, NCE's 1350V IGBTs offers superior conduction and switching performances, and easy parallel operation with exceptional avalanche ruggedness. This device is designed for soft switching applications.





### **Absolute Maximum Ratings**

Symbol	Description	Ratings	Units
V <sub>CES</sub>	Collector to Emitter Voltage	1350	V
$V_{GES}$	Gate to Emitter Voltage	+/-30	V
	Continuous Collector Current @T <sub>C</sub> =25°C	50	Α
I <sub>C</sub>	Continuous Collector Current @T <sub>C</sub> =100°C	25	Α
I <sub>CM</sub> (1)	Pulsed Collector Current	90	Α
I <sub>F</sub>	Diode Continuous Forward Current @T <sub>C</sub> =100°C	25	
I <sub>FM</sub>	Diode Maximum Forward Current	150	Α
В	Maximum Power Dissipation @T <sub>C</sub> =25°C	312	W
P <sub>D</sub>	Maximum Power Dissipation @T <sub>C</sub> =100°C	125	W
TJ	Operating Junction Temperature	-55 to +150	°C
T <sub>stg</sub>	Storage Temperature Range	-55 to +150	°C
	Maximum Lead Temp. for soldering Purposes, 1/8" from		
TL	case for 5seconds	300	°C

#### Notes:

1. Repetitive rating, Pulse width limited by max. junction temperature



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### **Thermal Characteristics**

Symbol	Parameter	Тур.	Max.	Units
$R_{JC}$	Thermal Resistance, Junction to Case	-	0.4	°C/W
$R_{JA}$	Thermal Resistance, Junction to Ambient	-	40	°C/W

## Electrical Characteristics of the IGBT $\tau_{c=25^{\circ}\text{C}}$

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
Off Char	acteristics					
D\/	Collector to Emitter	\/ =0\/ lo=1mA	1350			V
BV <sub>CES</sub>	Breakdown Voltage	V <sub>GE</sub> =0V, Ic=1mA		-	-	V
I <sub>CES</sub>	Collector Cut-Off Current	t V <sub>CE</sub> =1350V, V <sub>GE</sub> =0V		-	1	mA
$I_{GES}$	G-E Leakage Current	$V_{GE}$ =25V, $V_{CE}$ =0V	-	-	+/-250	nA
On Char	acteristics					
$V_{\text{GE}(th)}$	G-E Threshold Voltage	$I_C$ =25mA, $V_{CE}$ = $V_{GE}$	4.0	5.5	7.0	V
		I <sub>C</sub> =25A, V <sub>GE</sub> =15V	_	2	2.5	V
$V_{CE(sat)}$	Collector to Emitter Saturation	T <sub>C</sub> =25°C				
▼ CE(sat)	Voltage	I <sub>C</sub> =25A, V <sub>GE</sub> =15V	_	2.15	_	V
		T <sub>C</sub> =125°C		2.13		V
Dynamic	Characteristics	T				1
C <sub>ies</sub>	Input Capacitance		-	3700	-	pF
C <sub>oes</sub>	Output Capacitance	$V_{CE}$ =30V, $V_{GE}$ =0V,	-	130	-	pF
$C_{res}$	Reverse Transfer	f=1MHz	-	80	-	pF
Ores	Capacitance					
Switchin	g Characteristics		•		•	
$t_{d(on)}$	Turn-On Delay Time		_	50	-	ns
t <sub>r</sub>	Rise Time	V <sub>CC</sub> =600V,I <sub>C</sub> =25A,	-	60	90	ns
$t_{\text{d(off)}}$	Turn-Off Delay Time	$V_{CC}=000V,I_{C}=25A,$ $R_{G}=10\Omega,V_{GE}=15V,$	_	190	-	ns
$t_f$	Fall Time	Inductive Load,	-	100	180	ns
$E_{on}$	Turn-On Switching Loss	T <sub>C</sub> =25°C	-	4.1	6.2	mJ
$E_{off}$	Turn-Off Switching Loss	10-20 0	-	0.96	1.5	mJ
$E_{ts}$	Total Switching Loss		-	5.06	7.7	mJ
$t_{d(on)}$	Turn-On Delay Time		-	50	-	ns
$t_r$	Rise Time	\/ -600\/  -254	-	60	-	ns
$t_{\text{d(off)}}$	Turn-Off Delay Time	$V_{CC}$ =600V, $I_{C}$ =25A, $R_{G}$ =10 $\Omega$ , $V_{GE}$ =15V,	-	200	-	ns
$t_f$	Fall Time	Inductive Load,	-	154	-	ns
E <sub>on</sub>	Turn-On Switching Loss	T <sub>C</sub> =125°C	-	4.3	6.9	mJ
E <sub>off</sub>	Turn-Off Switching Loss	10-123 0	-	1.5	2.4	mJ
E <sub>ts</sub>	Total Switching Loss		-	5.8	9.3	mJ
Qg	Total Gate Charge	\/ -600\/   -25^	-	200	300	nC
Q <sub>ge</sub>	Gate to Emitter Charge	$V_{CC}$ =600V, $I_{C}$ =25A, $V_{GE}$ =15V	_	15	23	nC
Q <sub>gc</sub>	Gate to Collector Charge	v <sub>GE</sub> -13v	-	100	150	nC
	•					



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## Electrical Characteristics of Diode T<sub>C</sub>=25°C

Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Units
		I <sub>F</sub> =25A	T <sub>C</sub> =25°C	-	2.0	3.0	٧
$V_{FM}$	Diode Forward Voltage	1F-25A	T <sub>C</sub> =125°C	-	2.1		V
	Diode Reverse Recovery		T <sub>C</sub> =25°C	-	235	350	ns
t <sub>rr</sub>	Time		T <sub>C</sub> =125°C	-	300		ns
	Diode Peak Reverse	I <sub>F</sub> =25A,	T <sub>C</sub> =25°C	-	27	40	Α
I <sub>rr</sub>	Recovery Current	dI/dt=200A/us	T <sub>C</sub> =125°C	-	31		Α
	Diode Reverse Recovery		T <sub>C</sub> =25°C	-	3130	4700	uC
Q <sub>rr</sub>	Charge		T <sub>C</sub> =125°C	-	4650		uC



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### **Typical Performance Characteristics**

**Figure 1. Typical Output Characteristics** 

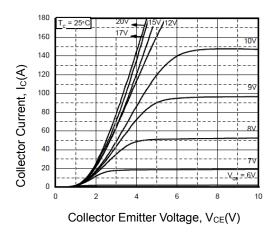


Figure 3. Saturation Voltage vs. Case

Temperature at Variant Current Level

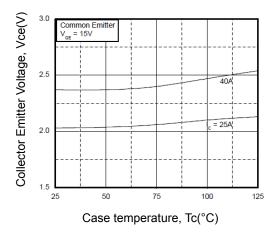


Figure 5. Saturation Voltage vs. V<sub>GE</sub>

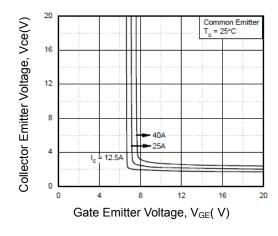


Figure 2. Typical Saturation Voltage Characteristics

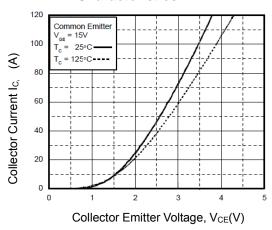


Figure 4. Saturation Voltage vs. V<sub>GE</sub>

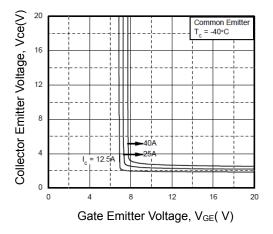
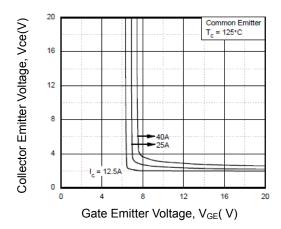


Figure 6. Saturation Voltage vs. V<sub>GE</sub>





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#### **Typical Performance Characteristics (Continued)**

Figure 7. Capacitance Characteristics

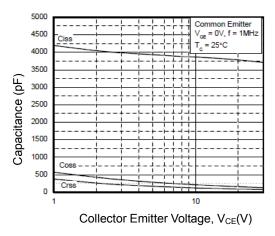


Figure 9. Turn-off Characteristics vs. Gate Resistance

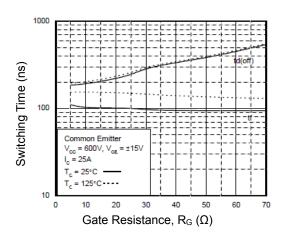


Figure 11. Turn-on Characteristics vs. Collector Current

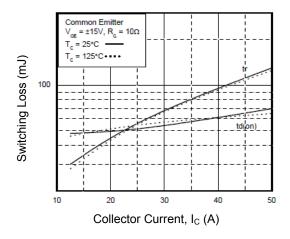


Figure 8. Turn-on Characteristics vs. Gate Resistance

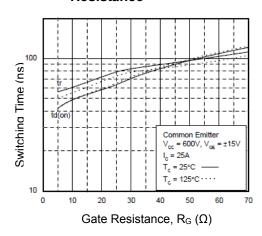


Figure 10. Switching Loss vs. Gate Resistance

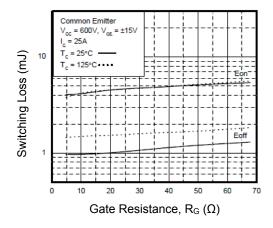
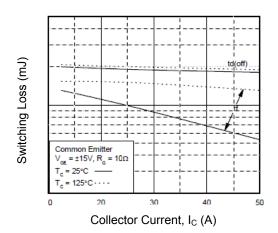


Figure 12. Turn-Off Characteristics vs.

Collector Current





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### **Typical Performance Characteristics (Continued)**

Figure 13. Switching Loss vs. Collector Current

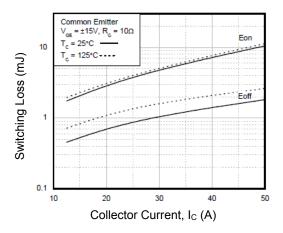


Figure 15. SOA Characteristics

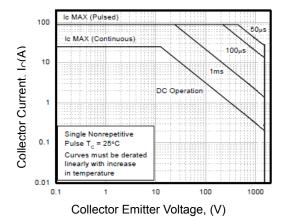


Figure 14. Gate Charge Characteristics

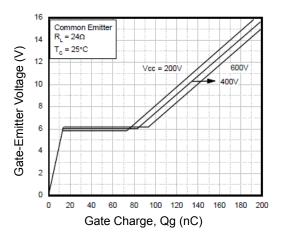
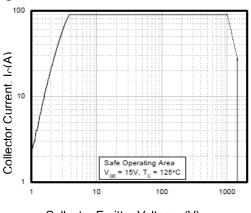
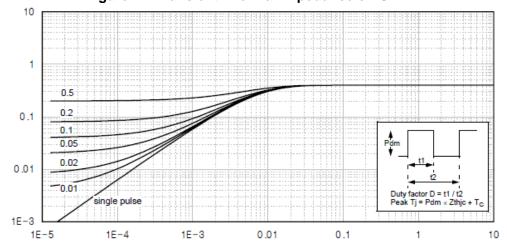


Figure 16. Turn-Off SOA



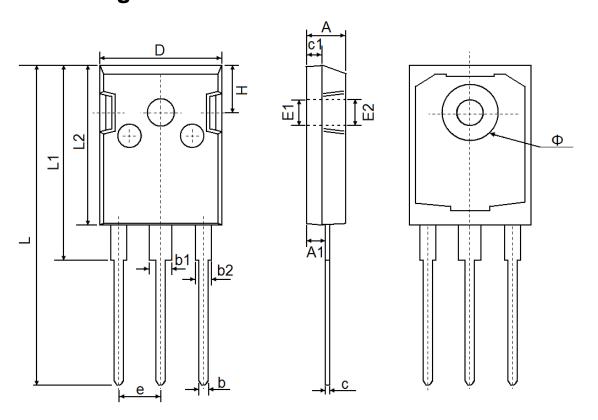
Collector Emitter Voltage, (V)

Figure 17. Transient Thermal Impedance of IGBT



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# **TO-247 Package Information**



Combal	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
А	4.850	5.150	0.191	0.200	
A1	2.200	2.600	0.087	0.102	
b	1.000	1.400	0.039	0.055	
b1	2.800	3.200	0.110	0.126	
b2	1.800	2.200	0.071	0.087	
С	0.500	0.700	0.020	0.028	
c1	1.900	2.100	0.075	0.083	
D	15.450	15.750	0.608	0.620	
E1	3.500 REF		0.138 REF		
E2	3.600 REF		0.142 REF		
L	40.900	41.300	1.610	1.626	
L1	24.800	25.100	0.976	0.988	
L2	20.300	20.600	0.799	0.811	
Φ	7.100	7.300	0.280	0.287	
е	5.450 TYP 0.215 TYP		TYP		
Н	5.98	0 REF	0.235 REF		



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